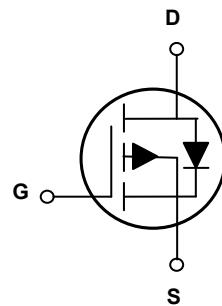


Main Product Characteristics

$V_{(BR)DSS}$	-60V
$R_{DS(ON)}$	48mΩ
I_D	-16A



TO-252 (DPAK)



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for POL applications, load switch and LED lighting
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF6905 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous ($T_c=25^\circ\text{C}$)	I_D	-16	A
Drain Current-Continuous ($T_c=100^\circ\text{C}$)		-10	
Drain Current-Pulsed ¹	I_{DM}	-64	A
Single Pulse Avalanche Energy ²	E_{AS}	51	mJ
Single Pulse Avalanche Current ²	I_{AS}	-32	A
Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	25	W
Power Dissipation-Derate above 25°C		0.2	W/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	5	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-50 To +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-50 To +150	$^\circ\text{C}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	-	-0.05	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-60\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	-1	μA
		$V_{\text{DS}}=-48\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	-10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-8\text{A}$	-	39	48	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-4\text{A}$	-	53	65	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.2	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	5	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-8\text{A}$	-	10	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3,4}	Q_g	$V_{\text{DS}}=-30\text{V}, I_{\text{D}}=-8\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	22.4	31	nC
Gate-Source Charge ^{3,4}	Q_{gs}		-	4.1	6	
Gate-Drain Charge ^{3,4}	Q_{gd}		-	5.2	7	
Turn-On Delay Time ^{3,4}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-30\text{V}, R_{\text{G}}=6\Omega$ $V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$	-	13	25	nS
Rise Time ^{3,4}	t_r		-	42.4	81	
Turn-Off Delay Time ^{3,4}	$t_{\text{d}(\text{off})}$		-	64.6	123	
Fall Time ^{3,4}	t_f		-	16.4	31	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	1250	1810	pF
Output Capacitance	C_{oss}		-	85	125	
Reverse Transfer Capacitance	C_{rss}		-	65	95	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	15	30	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V},$ Force Current	-	-	-16	A
Pulsed Source Current	I_{SM}		-	-	-64	A
Diode Forward Voltage	V_{sd}	$V_{\text{GS}}=0\text{V}, I_s=-1\text{A}, T_J=25^\circ\text{C}$	-	-	-1	V

Notes:

- Repetitive Rating: Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=-25\text{V}, V_{\text{GS}}=-10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=-32\text{A}, R_{\text{G}}=25\Omega$, Starting $T_J=25^\circ\text{C}$.
- Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

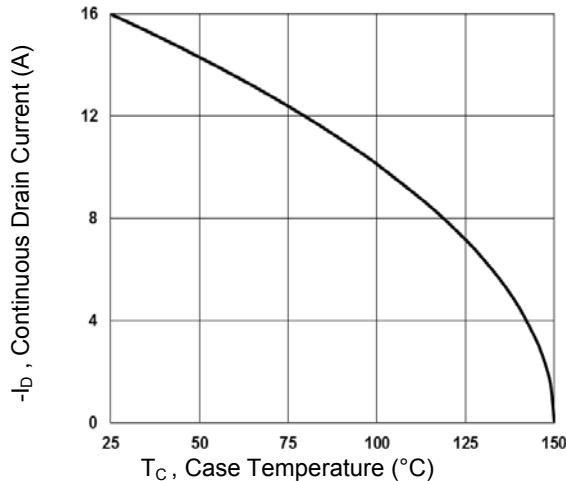


Figure 1. Continuous Drain Current vs. T_c

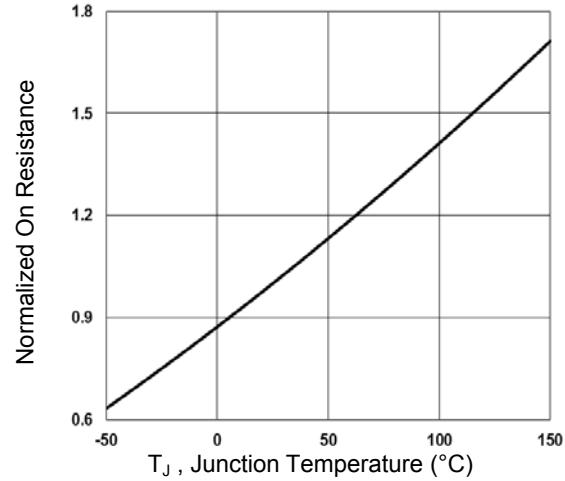


Figure 2. Normalized R_{DSON} vs. T_j

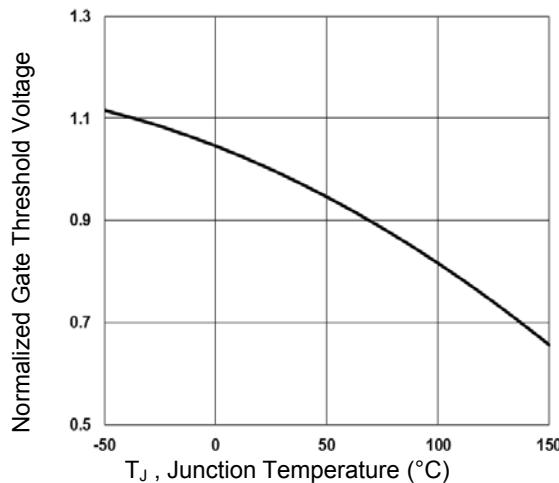


Figure 3. Normalized V_{th} vs. T_j

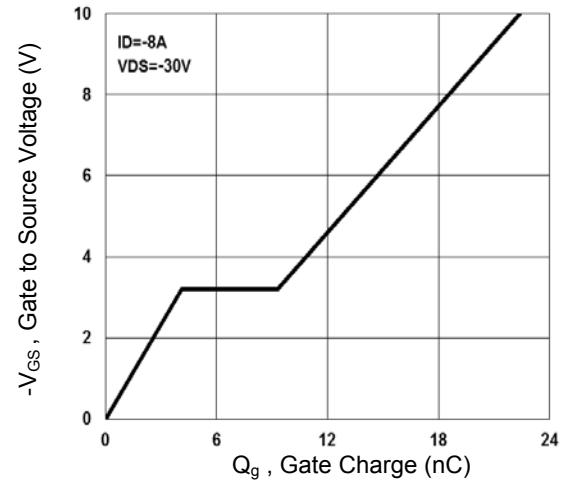


Figure 4. Gate Charge Waveform

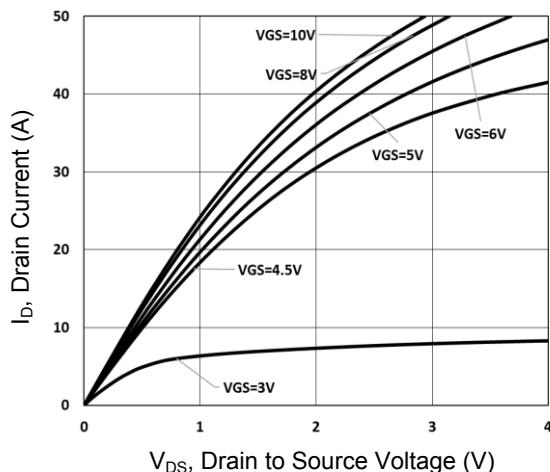


Figure 5. Typical Output Characteristics

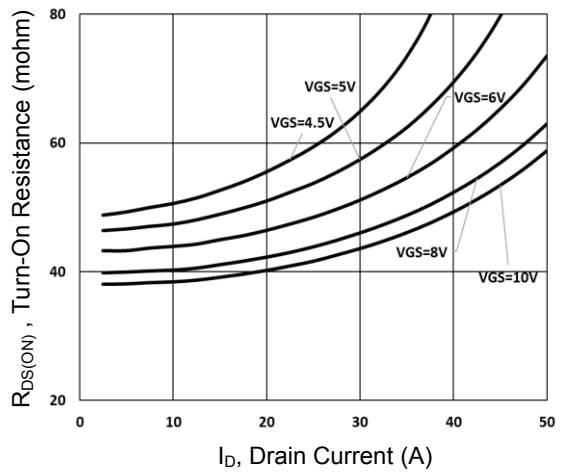
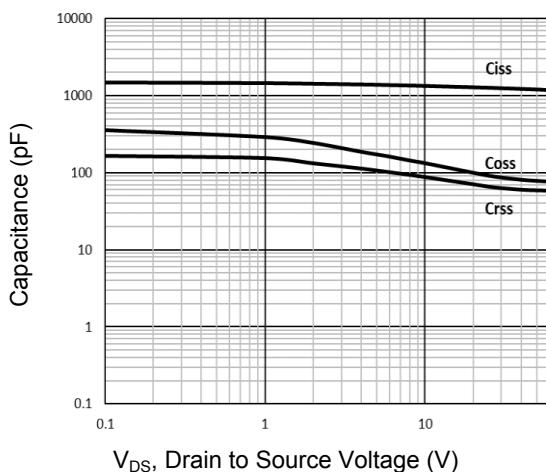


Figure 6. Turn-on Resistance vs. I_D

Typical Electrical and Thermal Characteristic Curves



V_{DS}, Drain to Source Voltage (V)

Figure 7. Capacitance Characteristics

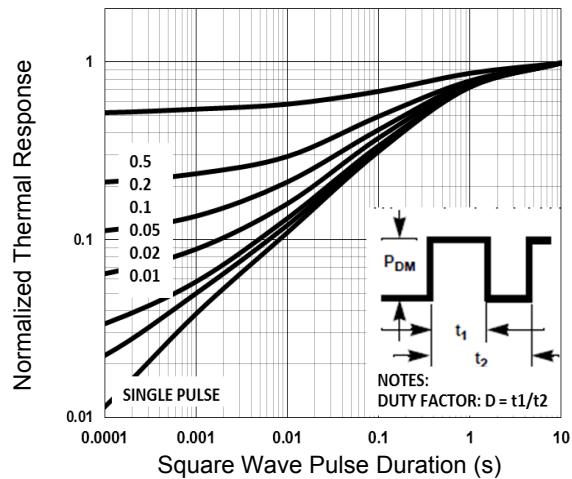
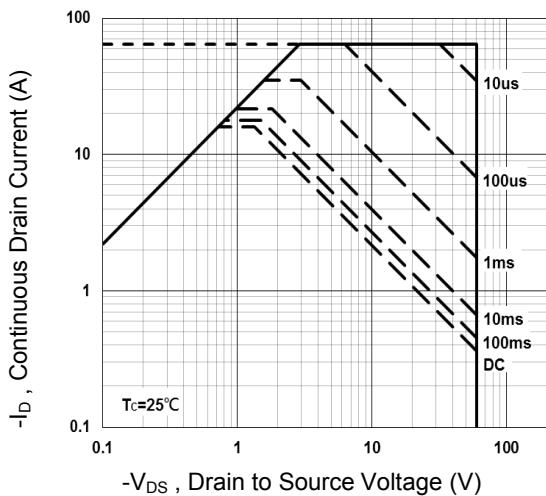


Figure 8. Normalized Transient Impedance



-V_{DS}, Drain to Source Voltage (V)

Figure 9. Maximum Safe Operation Area

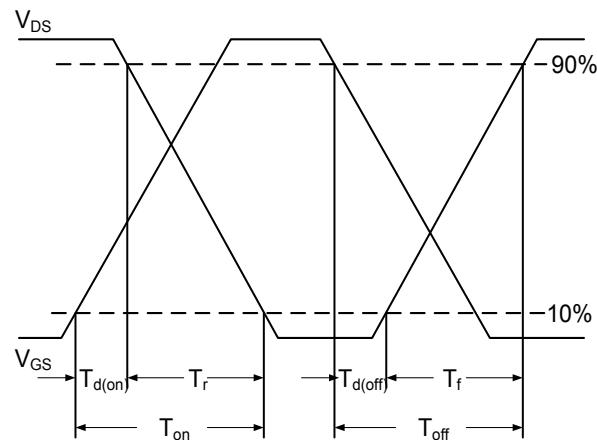


Figure 10. Switching Time Waveform

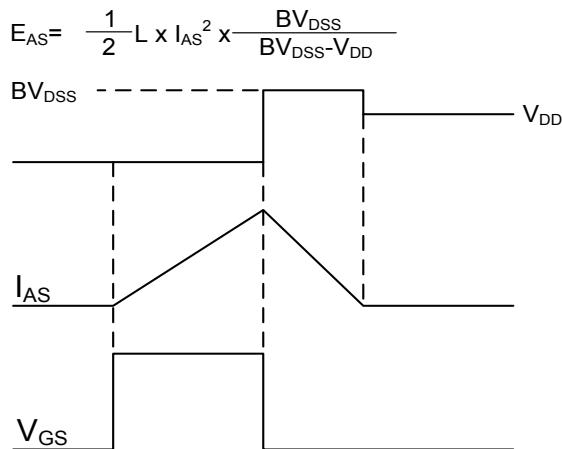
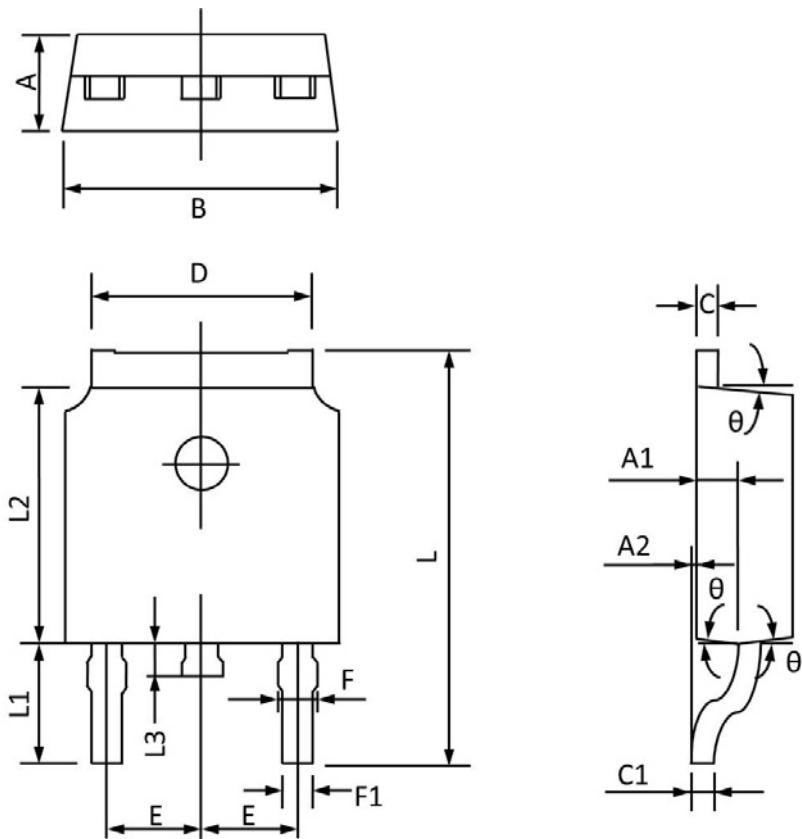


Figure 11. E_{AS} Waveform

Package Outline Dimensions

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°

Recommended Pad Layout

